



SOT1203

extremely thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON8
Package type industry code	XSON8
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	6-4-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.3	-	1.35	1.4	mm
E	package width		0.95	-	1	1.05	mm
A	seated height		[tbd]	-	[tbd]	0.35	mm
A ₂	package height		[tbd]	-	[tbd]	0.31	mm
e	nominal pitch		-	-	0.55	-	mm
n ₂	actual quantity of termination		-	-	8	-	



2. Package outline

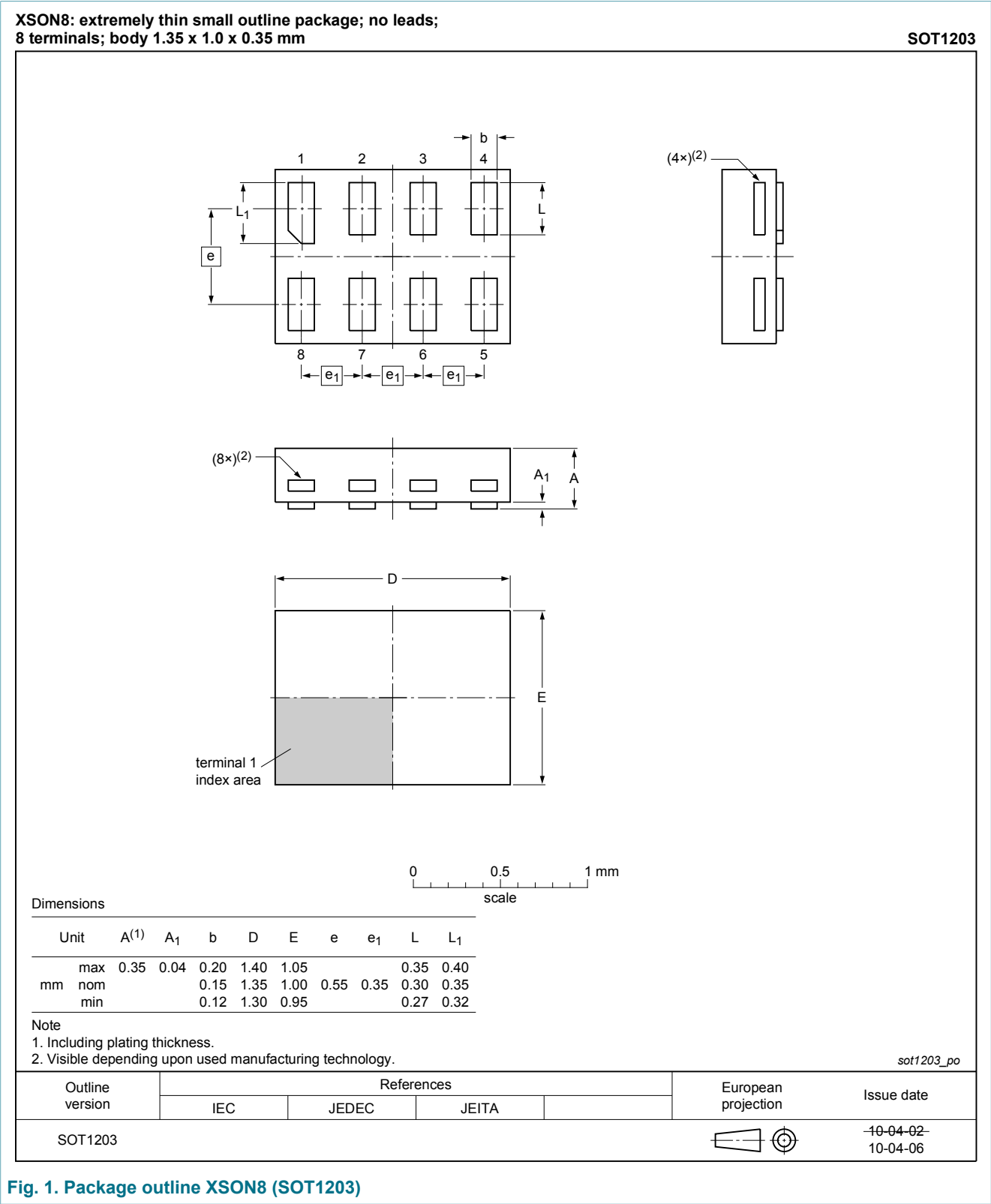


Fig. 1. Package outline XSON8 (SOT1203)

3. Legal information

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